

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	("6064114" "6617655" "6797544"). PN. and (semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:10
S2	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4) and mount	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:11
S3	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4) and (heat\$4 or anneal\$4 or thermal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:26
S4	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:12
S5	0	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode and "CMP"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S6	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13

EAST Search History

S7	9	(semiconductor or wafer or substrate) and terminal and plate and (resin near binder) and rigidity and bump and wir\$4 and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:13
S8	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and ((cut\$4 or dic\$4) near8 plate) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:36
S9	1	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4) and viscosity and liquid and (heat\$4 or thermal\$4 or anneal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:37
S10	2	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and bump and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:38
S11	10	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and wir\$4 and electrode and terminal and "CMP" and (cut\$4 or dic\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/20 14:41
S12	39	(semiconductor or wafer or substrate) and plate and (resin near4 binder) and "CMP" and (cut\$4 or dic\$4) and rigidity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:41
S13	50091	wiring near4 electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:08

EAST Search History

S14	2496	(wiring near4 electrode) and rigid\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:13
S15	1761	(wiring near4 electrode) and rigid\$4 and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S16	60	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S17	36	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:14
S18	9	(wiring near4 electrode) and rigid\$4 and plate and (resin near4 binder) and terminal and (semiconductor near4 element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/21 09:15
S19	9	(semiconductor near9 plate) and (resin near4 binder) and bump and (wir\$4 near9 layer) and ((cut\$4 or dic\$4) near9 plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:02
S20	6	(semiconductor near9 plate) and (resin near4 binder) and bump and (wir\$4 near9 layer) and ((cut\$4 or dic\$4) near9 plate) and align\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:07

EAST Search History

S21	109170	(semiconductor near element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:08
S22	17506	(semiconductor near element) near9 surface	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:08
S23	14	(semiconductor near element) near9 surface and plate and (resin near binder) and interpos\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:09
S24	4	(semiconductor near element) near9 surface and plate and (resin near binder) and interpos\$4 and bump and wir\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/04 13:09
S25	3	semiconductor and plate and (resin near binder) and rigidity and bump and wir\$4 and polish\$4 and (cut\$4 or dic\$4) and viscosity and (liquid near9 resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50
S26	241	semiconductor and plate and (resin near binder) and rigidity	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50
S27	13	semiconductor and plate and (resin near binder) and rigidity and bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 12:50

EAST Search History

S28	110217	(semiconductor near element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50
S29	21912	(semiconductor near element) and plate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50
S30	193	(semiconductor near element) and plate and (resin near binder)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 08:50
S31	20	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:31
S32	3	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and polish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:28
S33	3	(semiconductor near element) and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:36
S34	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:37

EAST Search History

S35	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4 and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 10:38
S36	49	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4 and electrode and (heat\$4 or thermal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:15
S37	23	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4 and electrode and (heat\$4 or thermal) and finish\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:28
S38	15	(resin near binder) near semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:20
S39	2	(resin near binder) near semiconductor and deform	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:17
S40	7	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and (cut\$4 or dic\$4) and electrode and polish\$4 and electrode and (heat\$4 or thermal) and finish\$4 and bump	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:30
S41	28	semiconductor and plate and (resin near binder) and rigid\$4 and wir\$4 and bump and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/17 12:42